

(News Release / Translation)

April 7, 2026

Name of company	V-Technology Co., Ltd.
Name of the Representative	Shigeto Sugimoto / President and CEO
Name of company	LE-TECHNOLOGY Co., Ltd.
Name of the Representative	Duk Lee / President, CEO
Person to contact:	Masahiro Ono / Chief of IR Office
TEL	045-338-1980

Notice of Correction:

V Technology Receives NEDO Order for DI Exposure System “LAMBDI”

Subject Press Release:

“V Technology Receives NEDO Order for DI Exposure System “LAMBDI”

Date of Release: April 7, 2026

Issuing Companies: V Technology Co., Ltd. and LE-TECHNOLOGY Co., Ltd.

We hereby announce that there was an error in the above-mentioned press release previously issued. We sincerely apologize for any inconvenience caused to our stakeholders.

Please find the corrections below. A revised version reflecting these corrections is attached for your reference.

Errata

Item	Before Correction	After Correction
Address of LE-TECHNOLOGY	DS Ichigaya Building 5F, 2-1 Ichigaya-Hachimancho, Shinjuku-ku, Tokyo	CIRCLES 2F, Ichigaya, 4-19 Yonbancho, Chiyoda-ku, Tokyo

【For inquiries regarding this matter:】

IR Department, V Technology Co., Ltd.

Masahiro Ono, General Manager



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(Revised)V Technology Receives NEDO Order for DI Exposure System “LAMBDI”

~ Secures Order for World’s First 0.5μm-Class System for Advanced Packaging ~

V Technology Co., Ltd. (Head Office: East Tower 9F, Yokohama Business Park, 134 Godo-cho, Hodogaya-ku, Yokohama, Kanagawa; President and CEO: Shigeto Sugimoto; hereinafter “the Company”) and its consolidated subsidiary, LE-TECHNOLOGY Co., Ltd. (Head Office: CIRCLES 2F, Ichigaya, 4-19 Yonbancho, Chiyoda-ku, Tokyo; President and CEO: Duk Lee ; hereinafter “LET”), have successfully developed the world’s first L/S = 0.5μm-class DI (Direct Imaging) exposure system “LAMBDI” for interposers and package substrates, and have received an order from NEDO (New Energy and Industrial Technology Development Organization) through Osaka Metropolitan University.

The Group began shipment of DI exposure systems capable of supporting 1μm-level wiring in August 2025, and has since achieved further improvements in resolution, leading to this order. Going forward, the Group will continue to develop innovative technologies that support the advancement of semiconductors and electronic devices, thereby contributing to the development of society.

The impact of this order on the Company’s financial results for the current fiscal year is expected to be minimal.